

**METHOD OF SELF-ANNEALING CONDUCTIVE LINES
THAT SEPARATES GRAIN SIZE EFFECTS
FROM ALLOY MOBILITY**

ABSTRACT OF THE DISCLOSURE

5 A method of forming a conductive structure such as a
copper conductive structure, line, or via is optimized for large grain
growth and distribution of alloy elements. The alloy elements can reduce
electromigration problems associated with the conductive structure. The
conductive structure is self-annealed or first annealed in a low
10 temperature process over a longer period of time. Another anneal is
utilized to distribute alloy elements.